

IN THE CLAIMS:

Please amend the claims as follows.

1. (Currently Amended) A stock sheet for a multilayer flexible wiring board comprising:  
  
a long flexible sheet-like substrate; and configured to be transported in a predetermined direction, and  
  
~~a plurality of wiring patterns directly arranged on a same surface of the substrate in a direction perpendicular to the predetermined direction, wherein the plurality of wiring patterns correspond to individual layers of a multilayer flexible wiring board.~~  
  
a plurality of wiring patterns formed on a same surface of the substrate, each wiring pattern having connecting electrodes through the substrate and exposed on both sides of the substrate,  
  
wherein a plurality of wiring patterns corresponding to individual layers of a multilayer flexible wiring board are directly arranged on the same surface of the substrate in the width direction, which is perpendicular to the longitudinal direction of the substrate, and a plurality of the directly arranged wiring patterns corresponding to multilayer flexible wiring boards are arranged in the longitudinal direction of the substrate.
2. (Cancelled).
3. (Withdrawn) A mask for exposure used in a photoetching process, comprising a sheet-like mask body, and a plurality of pattern holes arranged in a predetermined direction in the mask body and corresponding to individual layers of wiring boards of a multilayer flexible wiring board.

4. (Withdrawn) The mask of claim 3 wherein each pattern hole is arranged in a direction perpendicular to a transporting direction of the mask body.
5. (Withdrawn) The mask of claim 3 wherein each of the pattern holes corresponds to a wiring pattern.
6. (Withdrawn) The mask of claim 4 wherein each of the pattern holes corresponds to a wiring pattern.
7. (Withdrawn) A method for manufacturing a multilayer flexible wiring board comprising:  
using a mask for exposure in which a plurality of pattern holes corresponding to individual layers of wiring boards of a multilayer flexible wiring board are arranged in a predetermined direction in a sheet-like mask body; and exposing the mask body to light while it is transported in a predetermined direction.
8. (Withdrawn) The process of claim 7 wherein each pattern is arranged in a direction perpendicular to a transporting direction of the mask body.
9. (Withdrawn) The process of claim 7 wherein each of the pattern holes corresponds to a wiring pattern.
10. (Withdrawn) The process of claim 8 wherein each of the pattern holes corresponds to a wiring pattern.

11. (New) The stock sheet of claim 1, wherein the wiring patterns corresponding to individual layers of a multilayer flexible wiring board are arranged in a direction perpendicular to the longitudinal direction in which the substrate is transported.
12. (New) The stock sheet of claim 1, wherein the connecting electrodes comprise lands and bumps, wherein the lands are formed with the wiring patterns on one side of the substrate, the bumps are formed on the other side of the substrate and connected to the lands through the substrate, and the lands and the bumps are directly arranged in the width direction of the substrate in the group of wiring patterns corresponding to individual layers of a multilayer flexible wiring board.